We Claim:

1. A test apparatus for testing integrated modules, comprising a carrier substrate, the carrier substrate having a plurality of connection locations are arranged thereon, the connection locations being designed such that an integrated module is connected to a test unit connected to the carrier substrate via a connection location, the connection locations forming a connection array, the connection locations being arranged in groups within the connection array;

a data terminal provided for each connection location, the data terminals of connection locations of a respective group being connected to a respective different data bus;

a control terminal provided for each connection location, the control terminal selecting the integrated module for a test, the control terminals of connection locations of a respective group being connected to a control bus assigned to this group; and

an address and command terminal provided for each connection location, the address and command terminals of connection locations of a respective group being connected to an address and command bus via a respective switching means, which is assigned to the respective group and controlled by the control bus assigned to this group.

2. The test apparatus as claimed in claim 1, wherein the connection locations are arranged in rows and columns within the connection array,

the data terminals of connection locations of a respective column are connected to a data bus assigned to this column,

the control terminals of connection locations of a respective row are connected to a control bus assigned to this row, and

the address and command terminals of connection locations of a respective row are connected to a common address and command bus via a respective switching means, which may be controlled by the control bus assigned to this row.

3. The test apparatus as claimed in claim 1, wherein the carrier substrate is in the form of a burn-in test board.

4. A method for operating a test apparatus, the test apparatus including at least some connection locations on the carrier substrate being connected to integrated modules to be tested, the method comprising:

driving corresponding control bus(es) to simultaneously operate and drive modules of a number of groups of connection locations, wherein the number is less than the number of groups present on the carrier substrate; and

in simultaneously operating the modules of the number of groups, the groups being connected to the address and command bus via the respective switching means.

5. The method as claimed in claim 4, wherein the connection locations are arranged in rows and columns within the connection array and the modules of a number

of rows are simultaneously operated and driven, the number being smaller than the number of rows present on the carrier substrate, and

the modules of the number of rows which are simultaneously operated are connected to the address and command bus via the respective switching means.

6. The method as claimed in claim 4, wherein the modules which interchange data via the assigned data bus are operated and driven.

7. The method as claimed in claim 4, wherein the modules are subject to a functional test and beforehand and/or afterward to a burn-in test on the same carrier substrate.

8. The method as claimed in claim 7, wherein the modules are operated at a first operating frequency in the burn-in test and at a second operating frequency in the functional test, the first operating frequency being smaller than the second operating frequency.

9. The method as claimed in claim 7, wherein, during a burn-in test, driving the corresponding control buses simultaneously operates the modules of all groups, and

the modules of the groups are connected to the address and command bus via the respective switching means.

10. A test apparatus for testing integrated modules, comprising a carrier substrate, the carrier substrate having a plurality of connection locations are arranged thereon, the connection locations being designed such that an integrated module is connected to a test unit connected to the carrier substrate via a connection location, the connection locations forming a connection array, the connection locations being arranged in groups within the connection array;

a data terminal provided for each connection location, the data terminals of connection locations of a respective group being connected to a respective different data bus;

a control terminal provided for each connection location, the control terminal selecting the integrated module for a test, the control terminals of connection locations of a respective group being connected to a control bus assigned to this group; and

an address and command terminal provided for each connection location, the address and command terminals of connection locations of a respective group being connected to an address and command bus via a respective switch, which is assigned to the respective group and controlled by the control bus assigned to this group.

11. The test apparatus as claimed in claim 10, wherein the connection locations are arranged in rows and columns within the connection array,

the data terminals of connection locations of a respective column are connected to a data bus assigned to this column,

the control terminals of connection locations of a respective row are connected to a control bus assigned to this row, and

the address and command terminals of connection locations of a respective row are connected to a common address and command bus via a respective switch, which may be controlled by the control bus assigned to this row.

12. The test apparatus as claimed in claim 10, wherein the carrier substrate is in the form of a burn-in test board.

13. A method for operating a test apparatus, the test apparatus including at least some connection locations on the carrier substrate being connected to integrated modules to be tested, the method comprising:

driving corresponding control bus(es) to simultaneously operate and drive modules of a number of groups of connection locations, wherein the number is less than the number of groups present on the carrier substrate; and

in simultaneously operating the modules of the number of groups, the groups being connected to the address and command bus via the respective switch.

14. The method as claimed in claim 13, wherein the connection locations are arranged in rows and columns within the connection array and the modules of a number of rows are simultaneously operated and driven, the number being smaller than the number of rows present on the carrier substrate, and

the modules of the number of rows which are simultaneously operated are connected to the address and command bus via the respective switch.

15. The method as claimed in claim 13, wherein the modules which interchange data via the assigned data bus are operated and driven.

16. The method as claimed in claim 13, wherein the modules are subjected to a functional test and beforehand and/or afterward to a burn-in test on the same carrier substrate.

17. The method as claimed in claim 16, wherein the modules are operated at a first operating frequency in the burn-in test and at a second operating frequency in the functional test, the first operating frequency being smaller than the second operating frequency.

18. The method as claimed in claim 16, wherein during a burn-in test, driving the corresponding control buses simultaneously operates the modules of all groups, and the modules of the groups are connected to the address and command bus via the respective switch.